

Customer No.: 31561  
Docket No. 9223-US-PA  
Application No.: 10/064,644

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Hsu  
Application No. : 10/064,644  
Filed : Aug. 2, 2002  
For : FLIP-CHIP PACKAGE SUBSTRATE AND FLIP CHIP DIE  
Art Unit : 2826  
Examiner : WILLIAMS, ALEXANDER O

**TRANSMITTAL LETTER**

002-1-703-746-4000

(Via fax: 10 pages, followed by confirmation copy via courier)

Assistant Commissioner for Patents  
Arlington, Virginia 22202

Dear Sirs,

In response to the Notice of Allowance and Fee(s) due, dated December 12, 2003, attached herewith please find the relevant paper. Following the fax transmission, a hard copy via courier will also be forwarded to the Office.

Enclosed documents via courier will include:

- ☒ Issue Fee Transmittal (PTOL-85B) in duplicate
- ☒ Six (6) sheet(s) of formal drawings for FIGs. 1~3, 4A~4C, 5A and 5B for the above identified application.
- ☒ Prepaid return postcard
- ☒ Fax confirmation report

Please charge the fee in the amount of \$1639.00 for Issue Fee, Publication Fee and 3 soft copies to Account No. 50-2620 (Order No.: 9223-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

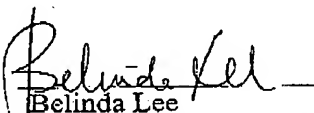


Patent

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Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: Feb 5, 2004

By:   
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